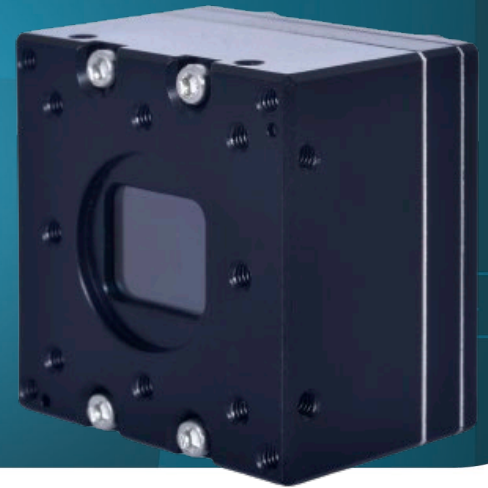


**HIGH-RESOLUTION UNCOOLED
THERMAL CORE**

Xenics
EXOSENS GROUP

Crius 640 Series



*ULTRA-COMPACT VGA
THERMAL IMAGING CORE*

KEY FEATURES



**VERY HIGH RESOLUTION - 12 μ m
FOR BETTER DRI RANGES**



**SMALL, LIGHT & LOW POWER
CONSUMPTION**

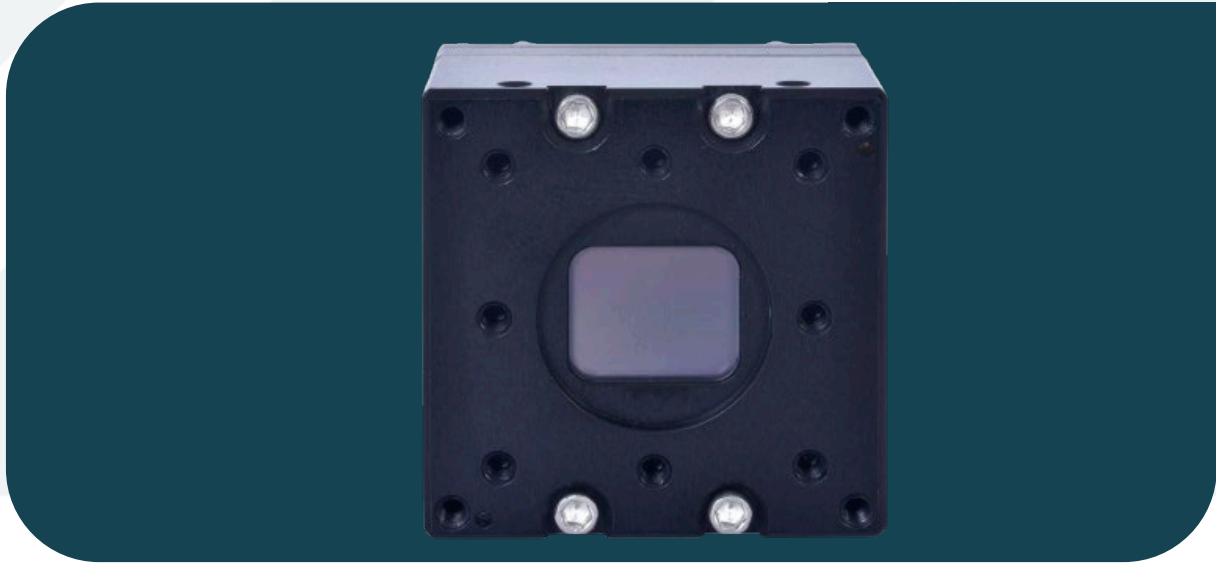


FRAME RATE UP TO 60 FPS

Thanks to its amazing compactness and the outstanding resolution, Crius series enable enhancement of electro optical-systems performances: major benefit is DRI (Detection Recognition Identification), a key factor for long range observation platforms in Search and Rescue or surveillance of sensitive areas for plants, border.

Its generic design ensures easy integration and retrofit of existing E/O systems in defense and security.

Crius 640 Series



KEY PERFORMANCES

Sensor	Micro-bolometer technology
Resolution / Pixel Pitch	640 x 480 pixels / 12 μ m
Spectral Range	8 – 14 μ m
Max NETD (F/1 ; 300K ; 30 Hz)	< 50 mK or < 40 mK
Operating temperature range	-40°C to +70°C
Power consumption (DF40)	< 1.2 W
Qualification	Industrial (Standard grade)

FUNCTIONS & INTERFACES

Image processing	BPC (Bad Pixel Correction), NUC (Non-Uniformity Correction), Shutterless NUC
Image optimisation	AGC (Automatic Gain Control)
Output options	CL, SDI, DF40
Additional option	On DF40: Handheld/manual control interface + micro display interface
Dimensions (L x B x H) (DF40)	30 x 30 x 23 mm ³
Weight (DF40)	< 38 g

PRODUCT SELECTOR GUIDE

XEN-000920 [Crius 640 50 mK (60 Hz)]	XEN-000921 [Crius 640 50 mK (9 Hz)]
XEN-000922 [Crius 640 40 mK (60 Hz)]	XEN-000923 [Crius 640 40 mK (9 Hz)]

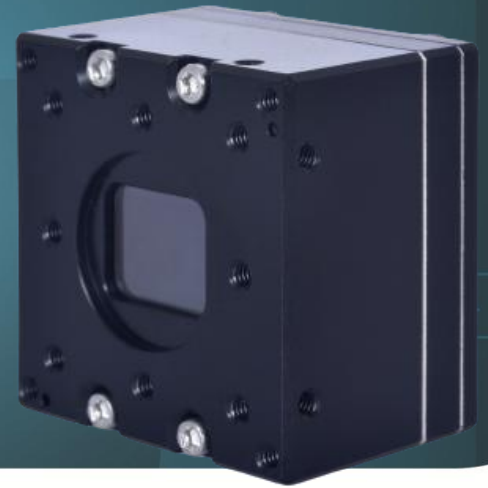
advancedimaging@exosens.com



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EXOSENS
REVEAL THE INVISIBLE

Crius XP 640 (NEW)



EXTREME PERFORMANCE WITH ULTRA-COMPACT VGA THERMAL IMAGING CORE

KEY FEATURES



ADVANCED SHUTTERLESS IMAGING WITH EMBEDDED CORRECTION



CONTOUR ENHANCEMENT: SHARPER DRI AND SUPERIOR OBJECT CLARITY



COLUMN AND TEMPORAL DENOISING: NETD halved from 40 mK to 20 mK



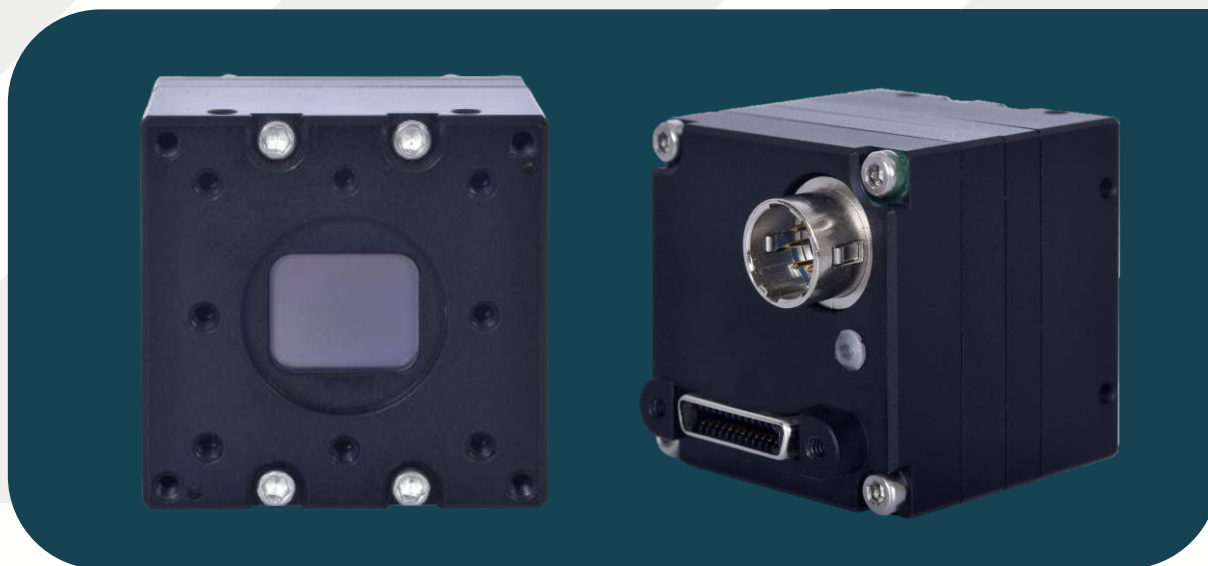
CONTRAST SHARPNESS CORE FOR AUTOFOCUS MANAGEMENT

The Crius XP (Extreme Performance) 640 is a cutting-edge uncooled LWIR thermal core, delivering ultra-sharp 640×480 resolution with a 12 μm pixel pitch and NETD <20 mK for exceptional thermal sensitivity.

Engineered for mission-critical defense applications, it features a next-gen shutterless algorithm for rapid imaging (<0.7s) and enhanced stability across extreme temperatures. Advanced contour enhancement deliver sharper contrast, superior dynamic range, and significantly improved DRI and object recognition.

Its compact SWaP design and flexible interface options ensure seamless integration into high-demand platforms, making it the ideal choice for modern thermal imaging systems.

Crius XP 640 (NEW)



KEY PERFORMANCES

Sensor	Micro-bolometer technology
Resolution / Pixel Pitch	640 x 480 pixels / 12 μ m
Spectral Range	8 – 14 μ m
Max NETD (F/1 ; 300K ; 30 Hz)	< 20 mK with denoising
Operating temperature range	-40°C to +70°C
Power consumption (DF40)	< 1.2 W
Qualification	MIL-STD-810G – Method 514 Vibration: 10Hz - 2kHz 13.95g per axis 10h per axis

FUNCTIONS & INTERFACES

Image processing	BPC (Bad Pixel Correction), NUC (Non-Uniformity Correction), Shutterless NUC
Image optimisation	AGC (Automatic Gain Control)
Output options	CL, SDI, DF40
Additional option	On DF40: Handheld/manual control interface + micro display interface
Dimensions (L x B x H) (DF40)	30 x 30 x 23 mm ³
Weight (DF40)	< 38 gr

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